



ASI-T-500MA4F6/B

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	120.7*75.80*4.67	MM
ACTIVE SIZE (W*H)	108.00*64.80	MM
PIXEL PITCH (W*H)	0.135*0.135	MM
NUMBER OF DOTS	800*480	
LCD DRIVER IC	ST7262	
CTP DRIVER IC	FT5446DQS	
INTERFACE TYPE	24-BIT RGB	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	ALL	O'CLOCK
GRAY SCALE INVERSION DIRECTION	N/A	O'CLOCK
BACKLIGHT TYPE	18-DIES WHITE LED	
TOUCH PANEL TYPE	CAPACITIVE	

[illegible]

Contents

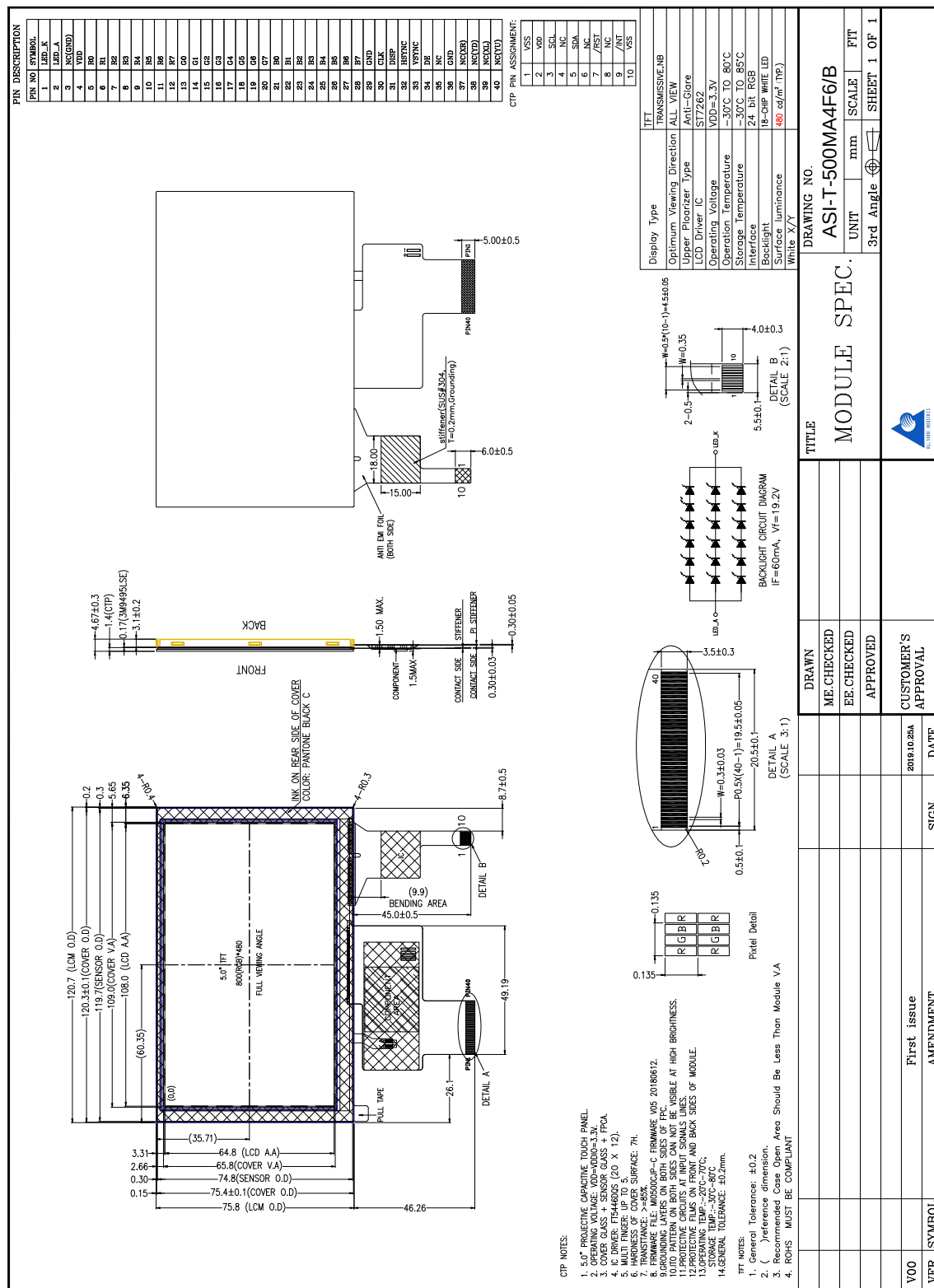
1. General Specification.....	4
2. Mechanical Drawing.....	5
3. Block Diagram.....	6
4. Interface Pin Function.....	7
5. Absolute Maximum Ratings.....	8
6. Electrical Characteristics.....	9
7. Optical Characteristics.....	10
8. Timing Characteristics.....	13
9. Standard Specification for Reliability.....	15
10. Specification of Quality Assurance.....	17
11. Handling Precaution.....	24
12. Packing Method.....	25

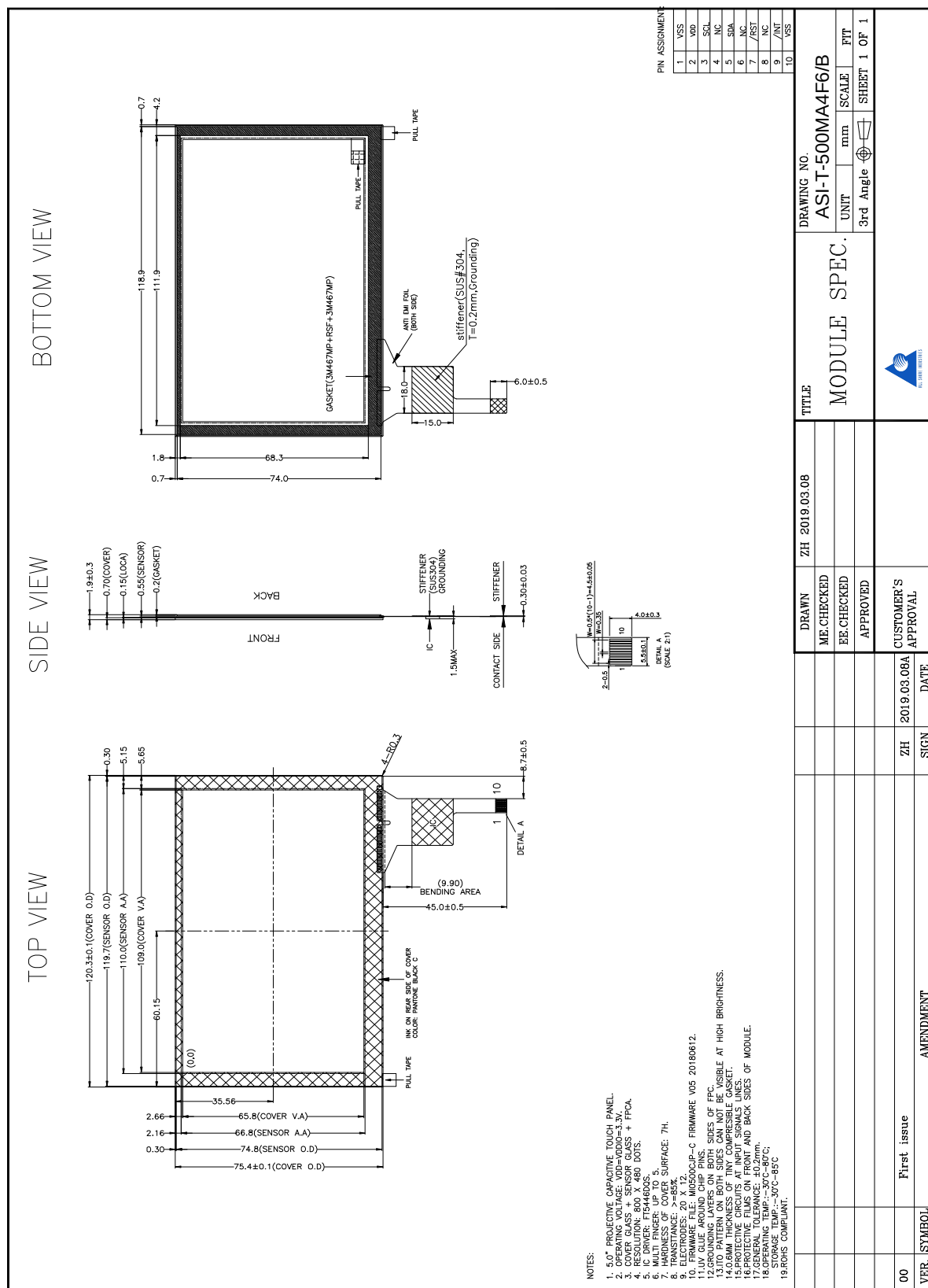
1. General Specification

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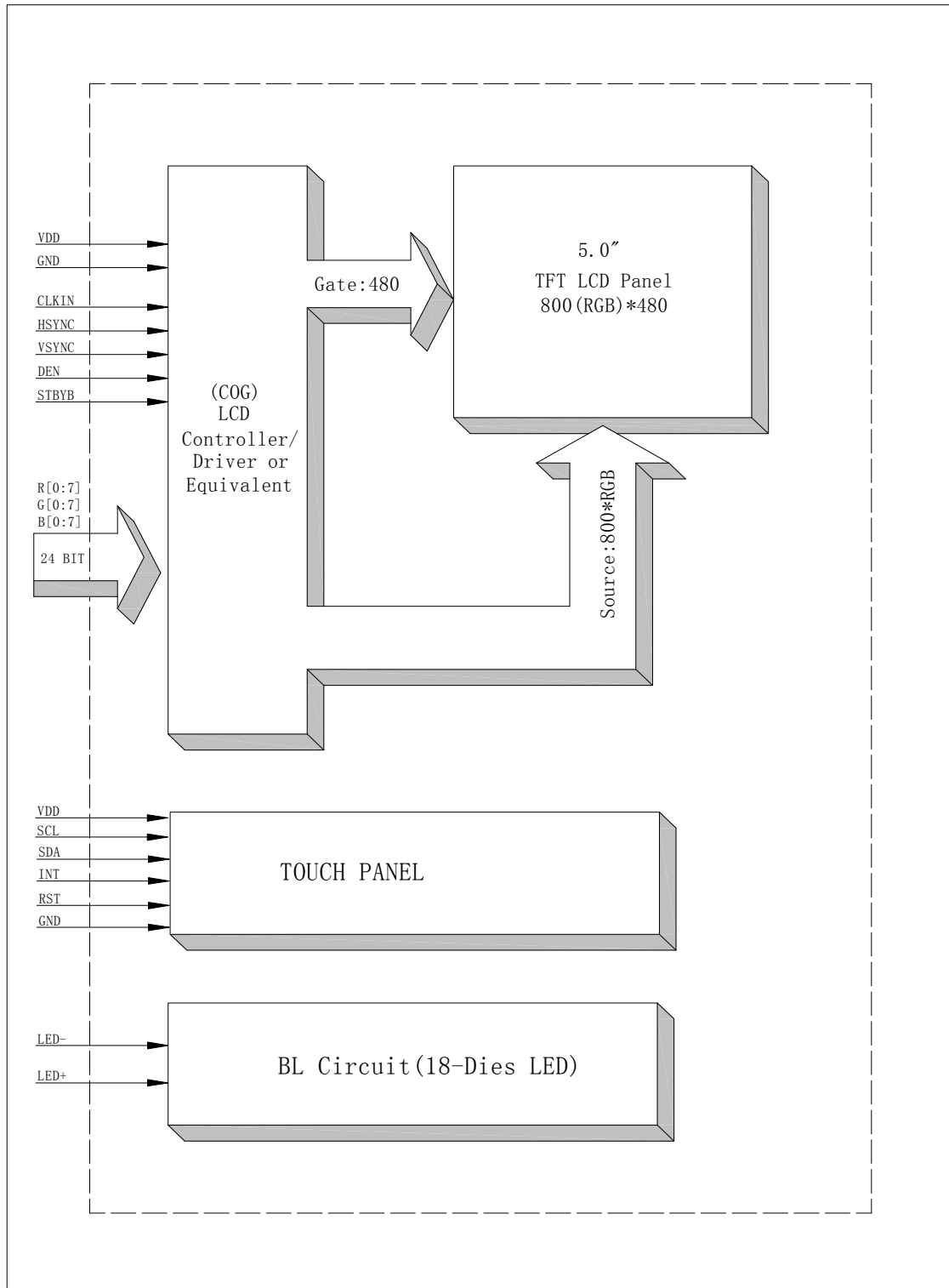


2. Mechanical Drawing





3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	LED-	Cathode of LED backlight.
2	LED+	Anode of LED backlight.
3	GND	Power ground.
4	VDD	Power supply.
5~12	R0~R7	8-bit digital Red data input.
13~20	G0~G7	8-bit digital Green data input.
21~28	B0~B7	8-bit digital Blue data input.
29	GND	Power ground.
30	CLKIN	Clock signal; latching data at the falling edge.
31	STBYB	Display control / standby mode selection. STBYB = "Low" : Standby; STBYB = "High" : Normal display(Default)
32	HSD	Horizontal sync signal; negative polarity.
33	VSD	Vertical sync signal; negative polarity.
34	DEN	Data input enable. Active High to enable the data input.
35	NC	No connection.
36	GND	Power ground.
37	NC	No connection.
38	NC	No connection.
39	NC	No connection.
40	NC	No connection.

CTP PIN

Pin No.	Symbol	Description
1	VSS	Ground
2	VDD	Power supply
3	SCL	I2C clock input.
4	NC	No connect
5	SDA	I2C data input and output.
6	NC	No connect
7	/RST	External Reset, Low is active.
8	NC	No connect
9	/INT	Interrupt request to the host, or Wake up request from the host.
10	VSS	Ground

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.5	V
Supply voltage for logic	VDD	-0.5	4.5	V
Supply current (One LED)	I _{LED}		30	mA
Operating temperature	T _{OP}	-30	+80	°C
Storage temperature	T _{ST}	-30	+85	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	3.0	3.3	3.6	V	
Supply Voltage for Logic	VDD	3.0	3.3	3.6	V	
Input Voltage	V _{IL}	GND	-	0.2VDD	V	
	V _{IH}	0.8 VDD	-	VDD		
Input leakage Current	I _{LKG}	-1		1	μA	
Supply Current	IDD	75	102	114	mA	

6.2 Backlight Driving Conditions

Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V _F	16.8	19.2	20.4	V	I _L =60mA
Current for LED Backlight	I _L		60		mA	
Power Consumption	P		1.152		W	
LED Life Time		30,000	50,000		Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25℃

6.3 CTP Electrical characteristics

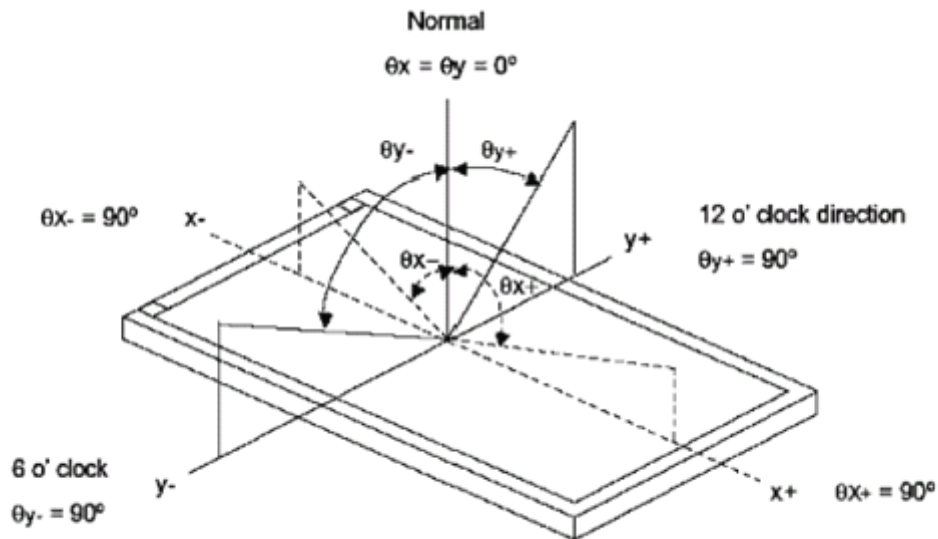
Item	Contents	Unit
Structure	G+G	
Outline dimension	120.3±0.1*75.4±0.1	mm
Outline dimension of sensor	119.7±0.2*74.8±0.2	mm
View area	109±0.2*65.8±0.2	mm
Drive IC	FT5446DQS	
Interface type	IIC	
IIC Address	0x70	
Supply voltage	2.8-3.3	V
I/O voltage	2.8-3.3	V
Number of touch point	5	point
Connector type	ZIF	
Transmittance of view area	≧ 85%	
Hardness	≧ 7H	

Item	Symbol	Value	Unit
Power supply voltage	VDD	2.7~3.6	V
I/O digital voltage	IOVCC	1.71~3.6	V
Operating temperature	Topr	-30 ~ +80	℃
Storage temperature	Tstg	-30 ~ +85	℃

7. Optical Characteristics

ITEM		SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
				MIN	TYP.	MAX		
Luminance		L	$I_L = 60\text{mA}$	380	480	720	Cd/m^2	
Contrast Ratio		CR	$\theta = 0^\circ$	1000	1500			
Response Time		T_{ON}	25°C		30	40	ms	
		T_{OFF}						
CIE Color Coordinate	Red	X_R	Viewing normal angle					
		Y_R						
	Green	X_G						
		Y_G						
	Blue	X_B						
		Y_B						
	White	X_W		0.304	0.344	0.384		
		Y_W		0.327	0.367	0.407		
Viewing Angle	Hor.	θ_{x+}	$CR \geq 10$	80	85	-	Degree	
		θ_{x-}		80	85	-		
	Ver.	θ_{y+}		80	85	-		
		θ_{y-}		80	85	-		
Uniformity	Un			75	80		%	

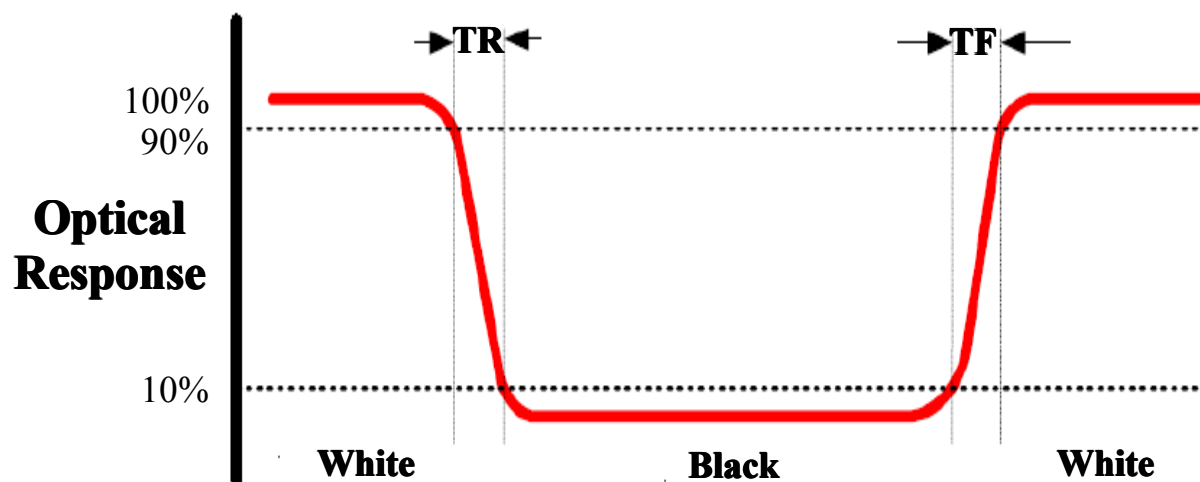
Note 1: Definition of Viewing Angle θ_x and θ_y :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

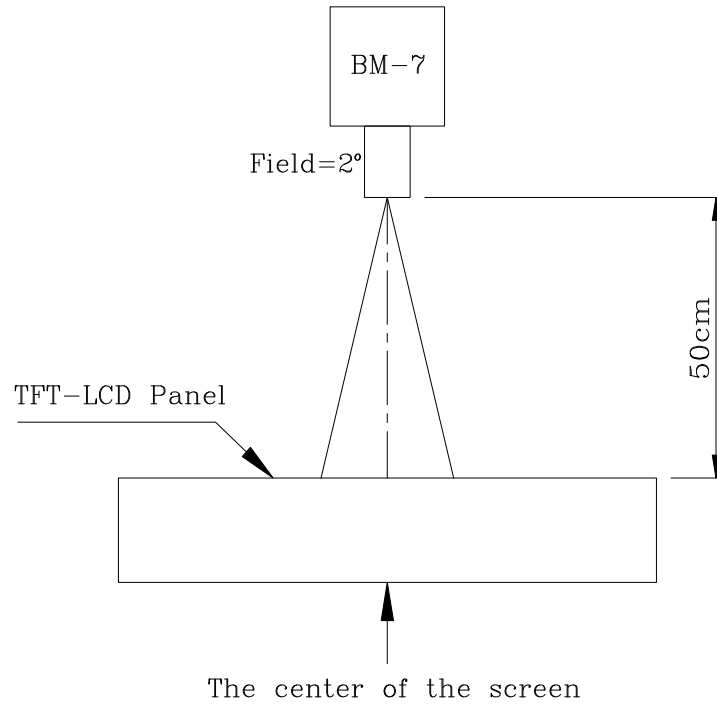
Note 3: Definition of Response Time(T_r , T_f)



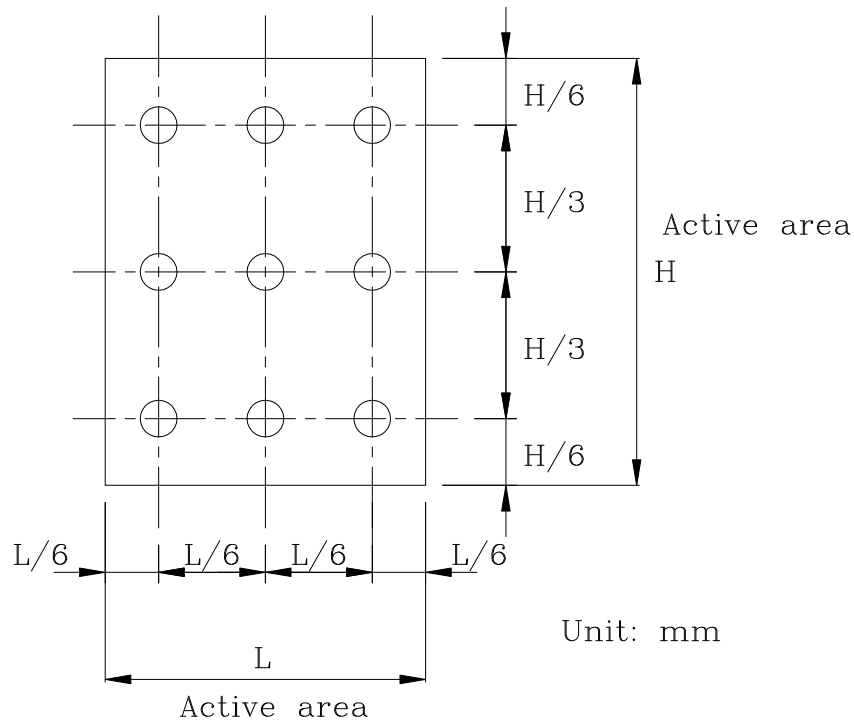
Note 4: Definition of Luminance

①The Brightness Test Equipment Setup

Field= 2° (As measuring “black” image, field= 2° is the best testing condition)

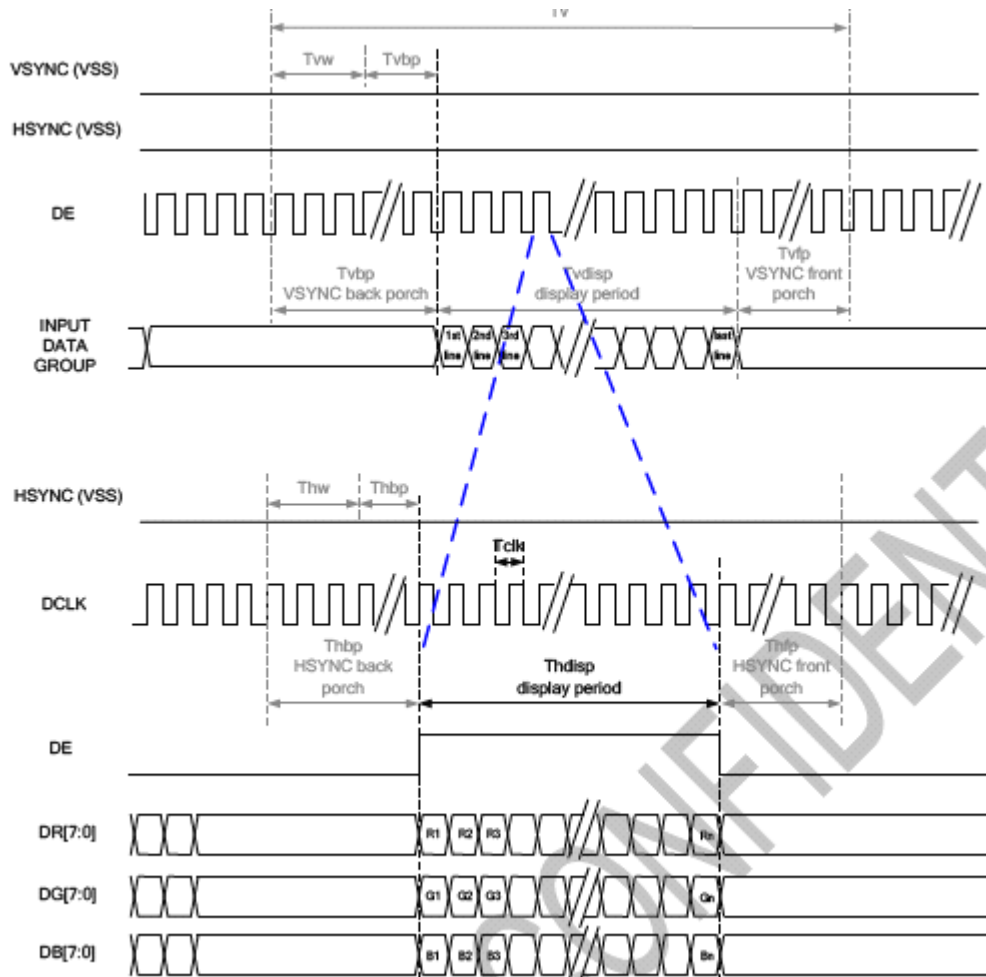


②The Brightness Test Point Setup



8. Timing Characteristics

8.1 RGB Mode Timing Diagram



8.2 RGB Timing Table

Parallel 24-bit RGB Interface Timing Table						
Item	Symbol	Min.	Typ.	Max.	Unit	Remark
DCLK Frequency	Fclk	23	25	27	MHz	
HSYNC	Period Time	Th	808	816	896	DCLK
	Display Period	Thdisp	800		DCLK	
	Back Porch	Thbp	4	8	48	DCLK
	Front Porch	Thfp	4	8	48	DCLK
	Pulse Width	Thw	2	4	8	DCLK
VSYNC	Period Time	Tv	488	496	504	HSYNC
	Display Period	Tvdisp	480		HSYNC	
	Back Porch	Tvbp	4	8	12	HSYNC
	Front Porch	Tvfp	4	8	12	HSYNC
	Pulse Width	Tvw	2	4	8	HSYNC

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description	Remarks
01	High temperature operation	The sample should be allowed to stand at 80°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.	Note 1 IEC60068-2-2, GB2423.2-89
02	Low temperature operation	The sample should be allowed to stand at -30°C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.	Note2 IEC60068-2-1 GB2423.1-89
03	High temperature storage	The sample should be allowed to stand at 85°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.	IEC60068-2-2 GB2423.2-89
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.	IEC60068-2-1 GB/T2423.1-89
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.	IEC60068-2-1 GB/T2423.3-2006
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.	Start with cold temperature,end with high temperature IEC60068-2-14, GB2423.22-87
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.	IEC61000-2-6 GB/T2423.5-1995
08	Packing drop test	According to ASTM-D-5327.	IEC60068-2-32 GB/T2423.8-1995
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times	IEC61000-4-2 GB/T17626.2-1998
		Contact: ±2KV 150pF/330Ω 5 time	

Note:1. Ts is the temperature of panel's surface.

2. Ta is the ambient temperature of sample.

3. Sample size for each test item is 3~5pcs.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5°C), normal humidity (50±10% RH), and in area not exposed to direct sun light.
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10. General Precautions

10.1. Safety

- Liquid crystal is poisonous. Do not put it in your mouth. If liquid crystal touches your skin or clothes, wash it off immediately by using soap and water.

10.2. Handling

- The LCD panel is plate glass. Do not subject the panel to mechanical shock or to excessive force on its surface.
- The polarizer attached to the display is easily damaged. Please handle it carefully to avoid scratch or other damages.
- To avoid contamination on the display surface, do not touch the module surface with bare hands.
- Keep a space so that the LCD panels do not touch other components.
- Put cover board such as acrylic board on the surface of LCD panel to protect panel from damages.
- Transparent electrodes may be disconnected if you use the LCD under environmental conditions where the condensation of dew occurs.
- Do not leave module in direct sunlight to avoid malfunction of the ICs.

10.3. Static Electricity

- Be sure to ground module before turning on power or operating module.
- Do not apply voltage which exceeds the absolute maximum rating value.

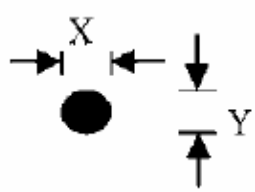
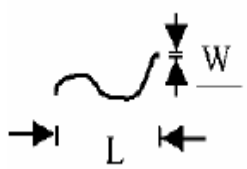
10.4. Storage

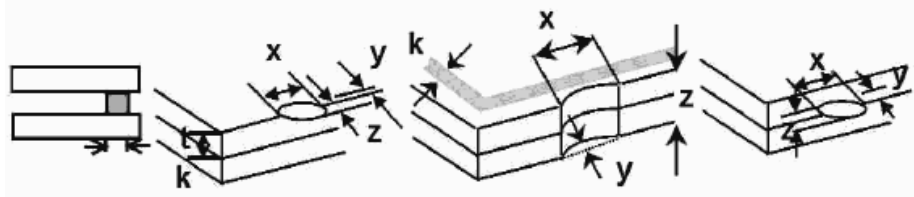
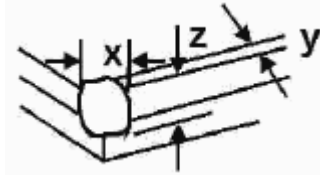
- Store the module in a dark room where must keep at $25\pm 10^{\circ}\text{C}$ and 65%RH or less.
- Do not store the module in surroundings containing organic solvent or corrosive gas.
- Store the module in an anti-electrostatic container or bag.

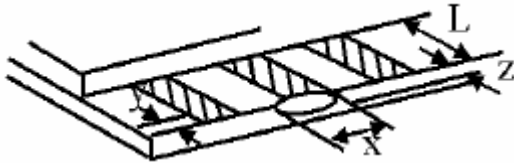
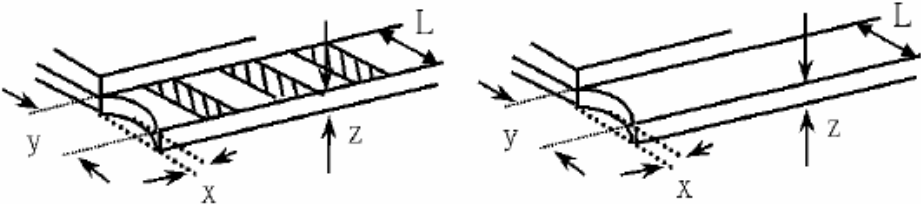
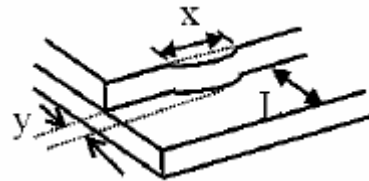
10.5. Cleaning

- Do not wipe the polarizer with dry cloth. It might cause scratch.
- Only use a soft cloth with IPA to wipe the polarizer, other chemicals might permanent damage to the polarizer.

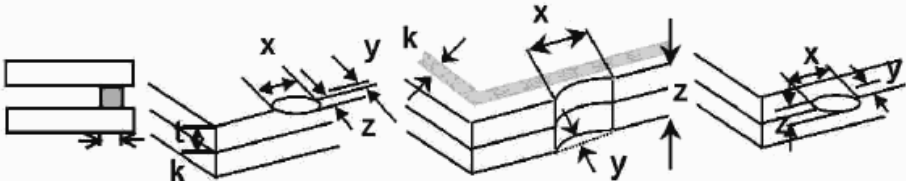
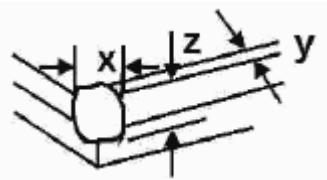
10.6 Inspection Specification

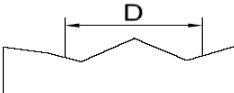
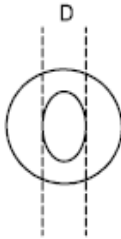
NO.	Item	Criterion	AQL																								
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65																								
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display < 0.25mm, no more than one spots. 2.2 Densely spaced: No more than three spots within 3mm.	2.5																								
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>2</td> </tr> <tr> <td>$0.25 < \Phi \leq 0.30$</td> <td>1</td> </tr> <tr> <td>$0.30 < \Phi$</td> <td>0</td> </tr> </table> * Densely spaced: No more than two spots within 3mm. 3.2 Line type: (As following drawing)  <table> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L < 2.5$</td> <td>$W < 0.08$</td> <td>1</td> </tr> <tr> <td>---</td> <td>$0.08 \leq W$</td> <td>Rejection</td> </tr> </table> * Densely spaced: No more than two lines within 3mm.	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L < 2.5$	$W < 0.08$	1	---	$0.08 \leq W$	Rejection	2.5
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---	$0.08 \leq W$	Rejection																									

NO.	Item	Criterion			AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ (mm)	Acceptable Q'ty	2.5
			$\Phi \leq 0.30$	Accept no dense	
			$0.30 < \Phi \leq 0.50$	0	
			$0.50 < \Phi \leq 1.00$	0	
			$1.00 < \Phi$	0	
			Total Q'ty	0	
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:			2.5
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	
		☉ Unit: mm ☉ If there are 2 or more chips, x is the total length of each chip 6.1.2 Corner crack:			
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	
		☉ Unit: mm ☉ If there are 2 or more chips, x is the total length of each chip			

NO.	Item	Criterion	AQL																
07	Glass crack	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:  <table> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> 7.2.2 Non-conductive portion:  <table> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged. 7.2.3 Substrate protuberance and internal crack  <table> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$X \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	2.5
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$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO.	Item	Criterion	AQL
08	Cracked glass	No crack is allowed.	2.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
10	Bezel	No scratches with $W > 0.1$ and $Length > 2.5mm$.	2.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	FPC damage per IPC guidelines.(IPC-A-610) Nicks or damage along the edges of the flexible printed circuitry and cutouts, providing the penetration does not exceed 50% of the distance from the edge to the nearest conductor to 2.5mm[0.1in], Whichever is less.	2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC. 13.3 Soldering per IPC guidelines.(IPC-A-610)	2.5 0.65

NO.	Item	Criterion	AQL												
14	Touch Panel Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:  <table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>$Z \leq t$</td><td>$\leq 1/2 k$ and not over viewing area</td><td>$x \leq 1/8a$</td></tr></table> ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 14.1.2 Corner crack:  <table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>$z \leq t$</td><td>$\leq 1/2 k$ and not over viewing area</td><td>$x \leq 1/8a$</td></tr></table> ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													
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$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													

NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	2.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$) , it is acceptable.	2.5										
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5										
18	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5										
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

11. Packing Method

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\%\text{RH}$. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than $280\pm 10^{\circ}\text{C}$ and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.